

Amendment to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1 to 28. (canceled)

Claim 29. (currently amended) A method for manufacturing an electrical circuit comprising a step of forming at least a part of the electrical circuit by impregnating a conductive polymer solution in a solvent or a conductive polymer dispersed liquid in a dispersant, in a receptive layer formed on a substrate, the conductive polymer exhibiting p-type conduction or n-type conduction, wherein the receptive layer contains inorganic particles and the receptive layer is porous.

Claim 30. (previously presented) The method for manufacturing the part of the electrical circuit of claim 29, comprising the steps of:

after impregnating the solution or the dispersed liquid containing the conductive polymer in the receptive layer, forming the part of the electrical circuit by evaporating the solvent of

the solution containing the conductive polymer or the dispersant of the dispersed liquid containing the conductive polymer.

Claim 31. (original) The method for manufacturing the electrical circuit of claim 30, wherein the solvent of the solution containing the conductive polymer or the dispersant of the dispersed liquid containing the conductive polymer contains 30 % or more of water.

Claim 32. (original) The method for manufacturing the electrical circuit of claim 30, wherein the solvent of the solution containing the conductive polymer or the dispersant of the dispersed liquid containing the conductive polymer contains 5 to 70 % by weight of a water soluble organic solvent.

Claim 33. (original) The method for manufacturing the electrical circuit of claim 32, wherein the solvent of the solution containing the conductive polymer or the dispersant of the dispersed liquid containing the conductive polymer contains 10 to 30 % by weight of a water soluble organic solvent.

Claim 34. (original) The method for manufacturing the electrical circuit of claim 30, wherein the solution or the dispersed liquid containing the conductive polymer has 0.001 to 1 % by weight of a

surfactant.

Claim 35. (previously presented) The method for manufacturing the electrical circuit of claim 34, wherein the surfactant is a non-ionic surfactant.

Claim 36. (original) The method for manufacturing the electrical circuit of claim 29, wherein the part of the electrical circuit is formed by ejecting the conductive polymer onto the receptive layer by a ink-jet printing method so as to impregnate the ejected conductive polymer in the receptive layer.

Claim 37. (original) The method for manufacturing the electrical circuit of claim 30, wherein the solution or the dispersed liquid containing the conductive polymer is impregnated in the receptive layer by ejecting the solution or the dispersed liquid containing the conductive polymer onto the receptive layer by a ink-jet printing method.

Claim 38. (original) The method for manufacturing the electrical circuit of claim 36, wherein an amount of the conductive polymer

impregnated in the receptive layer is controlled by controlling an amount of the ejected conductive polymer per unit area.

Claim 39. (original) The method for manufacturing the electrical circuit of claim 37, wherein an amount of the conductive polymer impregnated in the receptive layer is controlled by controlling an amount of the ejected solution or the dispersed liquid containing the conductive polymer per unit area.

Claim 40. (previously presented) The method for manufacturing the electrical circuit of claim 29,

wherein:

the conductive polymer is an oligomer having a repeat number of 4 to 19 or a polymer having a repeat number of 20 or more; and

the conductive polymer has a repeat unit of thiophene, vinylene, thienylene vinylene, phenylene vinylene, p-phenylene or a substituent compound thereof.

Claim 41. (original) The method for manufacturing the electrical circuit of claim 40, wherein the conductive polymer is an oligomer or a polymer having thiophene or substituted thiophene as a repeat unit.

Claim 42. (original) The method for manufacturing the electrical

circuit of claim 40, wherein the oligomer or the polymer contains a dopant.

Claim 43. (previously presented) The method for manufacturing the electrical circuit of claim 29, wherein an electrical conductivity of the conductive polymer is 0.01 S/cm or more.

Claim 44. (original) The method for manufacturing the electrical circuit of claim 43, wherein the electrical conductivity of the conductive polymer is 1 S/cm or more.

Claim 45. (canceled)

Claim 46. (canceled)

Claim 47. (currently amended) The method for manufacturing the electrical circuit of claim [[46]] 29, wherein the inorganic particles are fumed silica particles ~~prepared by a vapor-deposition method~~.

Claim 48. (currently amended) The method for manufacturing the electrical circuit of claim [[46]] 29, wherein an average particle diameter of the inorganic particles is 0.003 to 0.2 μm .

Claim 49. (original) The method for manufacturing the electrical circuit of claim 48, wherein the average particle diameter of the inorganic particles is 0.005 to 0.1 μ m.

Claim 50. (currently amended) The method for manufacturing the electrical circuit of claim [[46]] 29, wherein:

the receptive layer further contains a hydrophilic binder;
and

a weight ratio of the inorganic particles to the hydrophilic binder is between 2 : 1 and 20 : 1.

Claim 51. (previously presented) The method for manufacturing the electrical circuit of claim 29, wherein the substrate is a polymer.

Claims 52 to 74. (canceled)

Claim 75. (previously presented) A method for manufacturing an electrical circuit comprising a step of forming at least a part of the electrical circuit by impregnating a conductive polymer solution or a conductive polymer dispersed liquid in a receptive layer formed on a substrate, the conductive polymer exhibiting p-type conduction or n-type conduction, wherein

the receptive layer is porous; and

the receptive layer comprises at least particles selected from the group consisting of alumina particles, pseudo boehmite particles, colloidal silica particles and fumed silica particles.

Claim 76. (previously presented) A method for manufacturing an electrical circuit comprising a step of forming at least a part of the electrical circuit by impregnating a conductive polymer solution or a conductive polymer dispersed liquid in a receptive layer formed on a substrate, the conductive polymer exhibiting p-type conduction or n-type conduction, wherein

the receptive layer contains inorganic particles and a hydrophilic binder; and

a weight ratio of the inorganic particles to the hydrophilic binder is between 2 : 1 and 20 : 1.